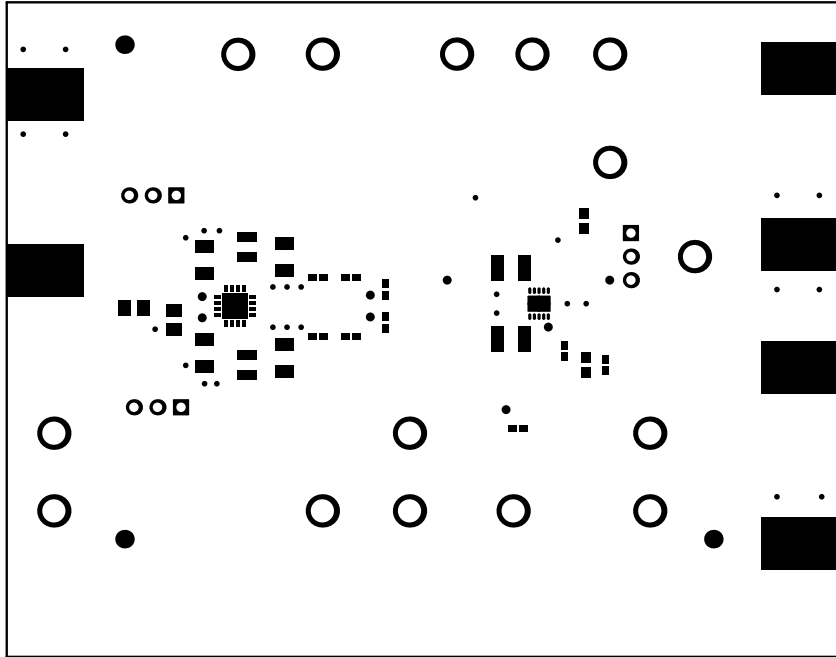
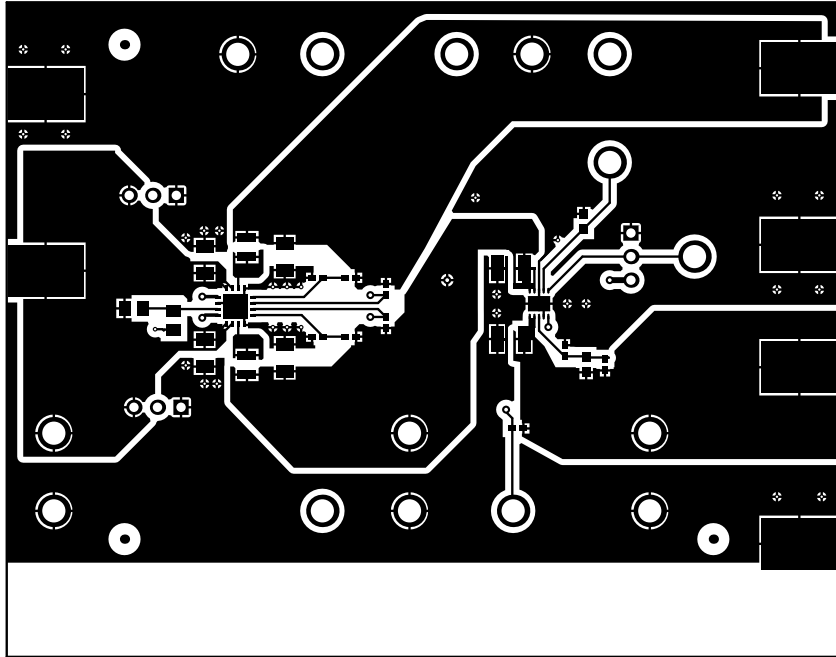


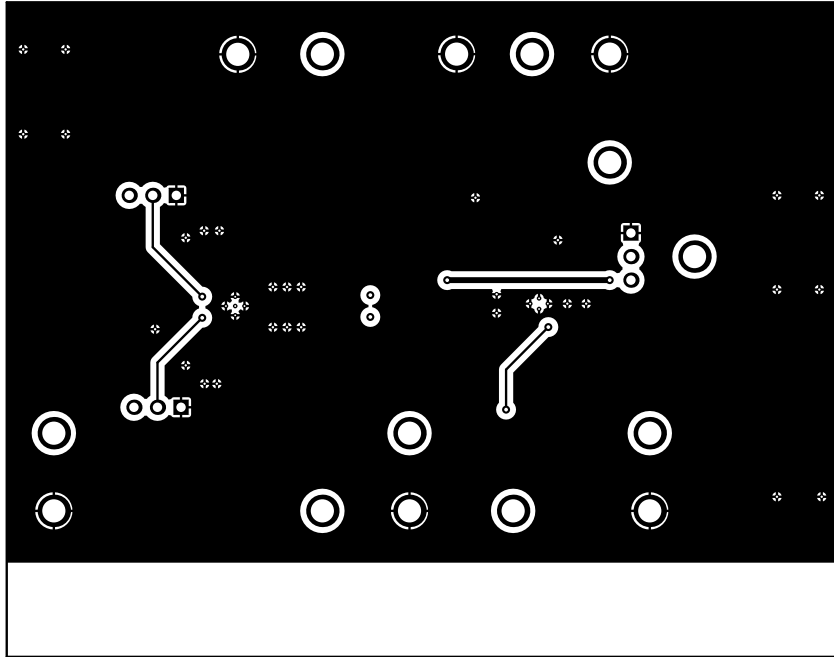
ALL ARTWORK VIEWED FROM TOP SIDE	BOARD #: TIDA-01322	REV: E1	SUN REV: Not In VersionControl
LAYER NAME = Top Overlay	TID #: N/A		
PLOT NAME = Top Overlay	GENERATED : 16.3.2017 10:20:00	TEXAS INSTRUMENTS	



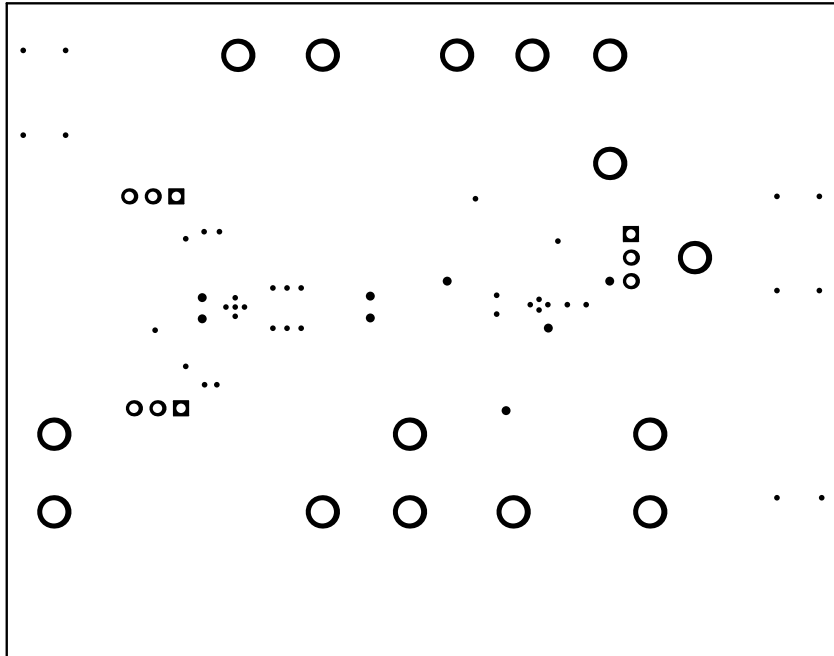
ALL ARTWORK VIEWED FROM TOP SIDE	BOARD #: TIDA-01322	REV: E1	SUN REV: Not In VersionControl
LAYER NAME = Top Solder	TID #: N/A		
PLOT NAME = Top Solder Mask	GENERATED : 16.3.2017 10:20:00	TEXAS INSTRUMENTS	



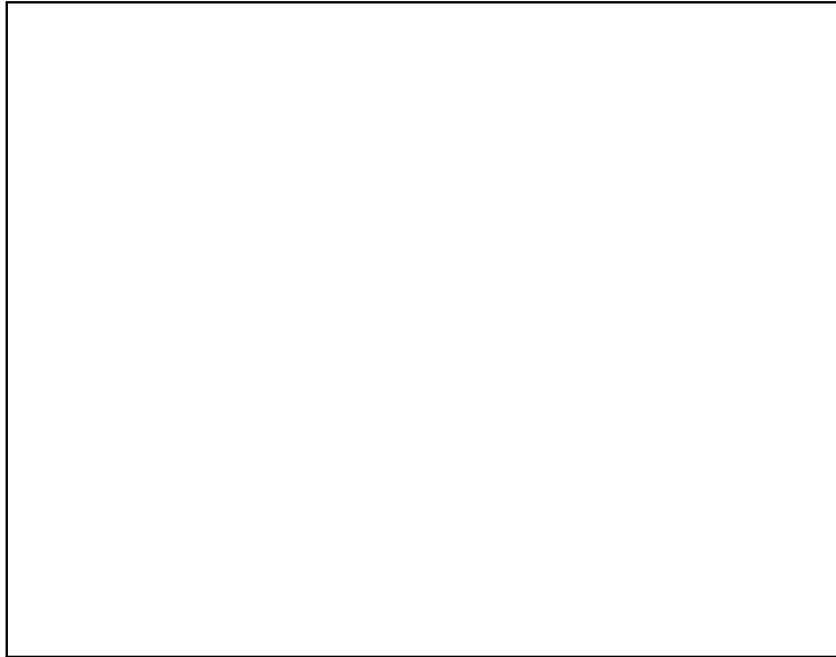
ALL ARTWORK VIEWED FROM TOP SIDE	BOARD #: TIDA-01322	REV: E1	SUN REV: Not In VersionControl
LAYER NAME = Top Layer	TID #: N/A		
PLOT NAME = Top Layer	GENERATED : 16.3.2017 10:20:01	TEXAS INSTRUMENTS	



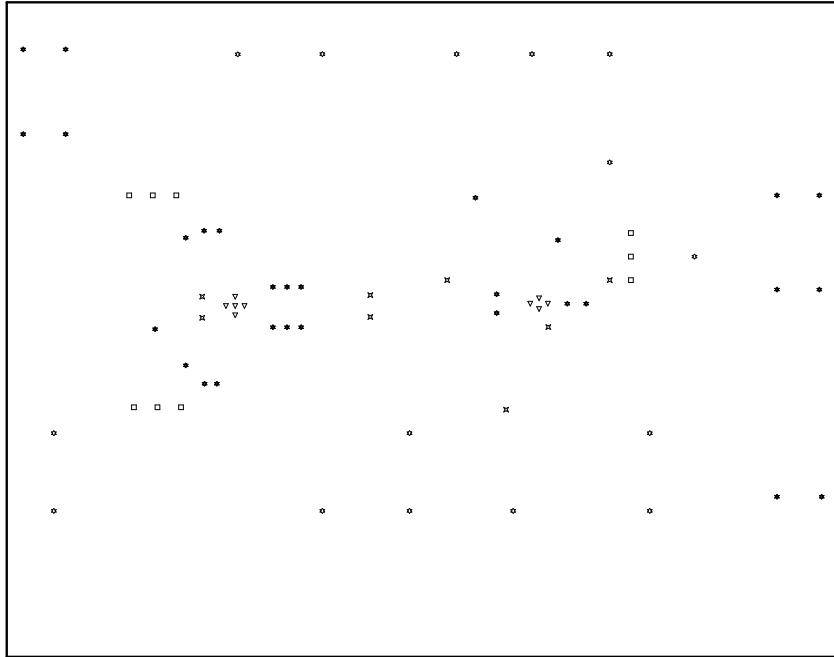
ALL ARTWORK VIEWED FROM TOP SIDE	BOARD #: TIDA-01322	REV: E1	SVN REV: Not In VersionControl
LAYER NAME = Bottom Layer	TID #: N/A		
PLOT NAME = Bottom Layer	GENERATED : 16.3.2017 10:20:01	TEXAS INSTRUMENTS	



ALL ARTWORK VIEWED FROM TOP SIDE	BOARD #: TIDA-01322	REV: E1	SUN REV: Not In VersionControl
LAYER NAME = Bottom Solder	TID #: N/A		
PLOT NAME = Bottom Solder Mask	GENERATED : 16.3.2017 10:20:01	TEXAS INSTRUMENTS	

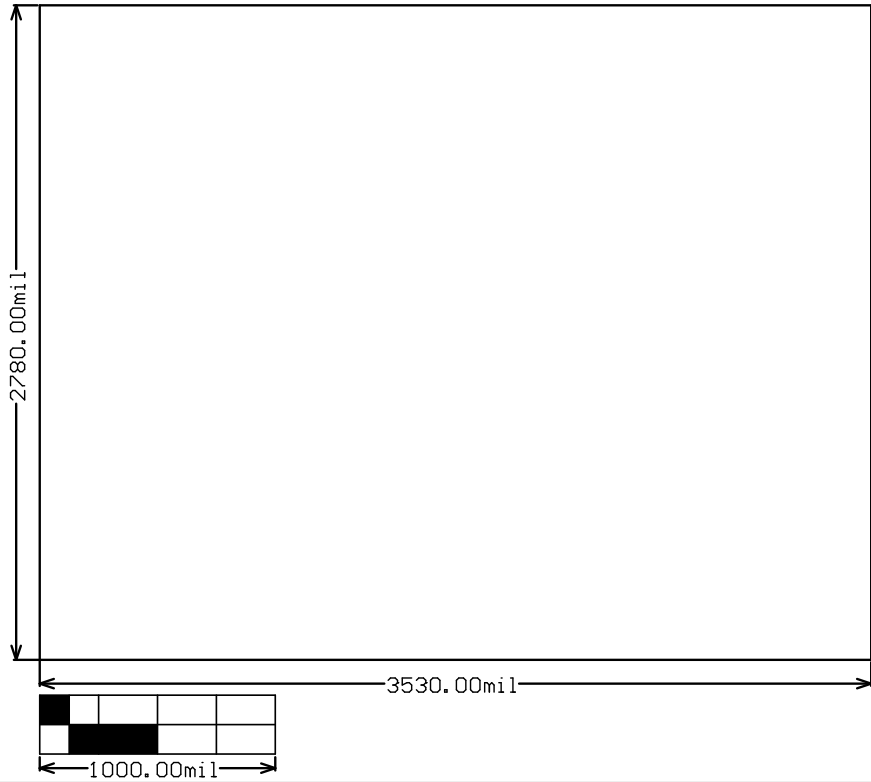


ALL ARTWORK VIEWED FROM TOP SIDE	BOARD #: TIDA-01322	REV: E1	SUN REV: Not In VersionControl
LAYER NAME = Bottom Overlay	TID #: N/A		
PLOT NAME = Bottom Overlay	GENERATED : 16.3.2017 10:20:01	TEXAS INSTRUMENTS	



Symbol	Quantity	Finished Hole Size	Plated	Hole Type	Drill Layer Pair	Hole Tolerance
▽	9	7.87mil (0.200mm)	PTH	Round	Top Layer - Bottom Layer	
✱	29	10.00mil (0.254mm)	PTH	Round	Top Layer - Bottom Layer	
✕	8	16.00mil (0.406mm)	PTH	Round	Top Layer - Bottom Layer	
□	9	40.00mil (1.016mm)	PTH	Round	Top Layer - Bottom Layer	
✱	15	98.43mil (2.500mm)	PTH	Round	Top Layer - Bottom Layer	
	70 Total					

ALL ARTWORK VIEWED FROM TOP SIDE	BOARD #: TIDA-01322	REV: E1	SUN REV: Not In VersionControl
LAYER NAME = Drill Drawing	TID #: N/A		
PLOT NAME = Drill Drawing	GENERATED : 16.3.2017	10:20:01	TEXAS INSTRUMENTS



ALL ARTWORK VIEWED FROM TOP SIDE	BOARD #: TIDA-01322	REV: E1	SUN REV: Not In VersionControl
LAYER NAME = M2 Board Dimensions	TID #: N/A		
PLOT NAME = Board Dimensions	GENERATED : 16.3.2017 10:20:01	TEXAS INSTRUMENTS	



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Mailing Address: Texas Instruments, Post Office Box 655303, Dallas, Texas 75265  
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